

CGHV35400F1

Rev. V3

Features

- 400 W Minimum Output Power
- Large Signal Gain: 13 dB
- Drain Efficiency: 65%
- Internally Matched: 50 Ω
- High Temperature Operation
- RoHS* Compliant

Applications

• Civil & Military Pulsed Radar Amplifiers

Description

The CGHV35400F1 is a gallium nitride (GaN) amplifier designed specifically with high efficiency and high gain for the 2.9 - 3.5 GHz S-Band radar band.

The device has been developed with long pulse capability to meet the developing trends in radar architectures.

The amplifier is matched to 50-ohms on the input and 50-ohms on the output. The CGHV35400F1 is based on the high power density 50 V, 0.4 μ m GaN on silicon carbide (SiC) manufacturing process.

The amplifier is supplied in a ceramic/ metal flange package of type 440226.

Typical RF Performance:

Measured in Evaluation Test Fixture¹ at $P_{IN} = 46$ dBm, 2 msec pulse width and 20% Duty Cycle.

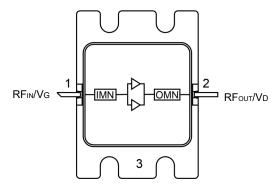
• $V_{DS} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, T_{C} = 25^{\circ}\text{C}$

Frequency (GHz)	Output ¹ Power (dBm)	Power ¹ Gain (dB)	η₀¹ (%)
2.9	57.1	11.1	69
3.2	56.9	10.9	64
3.5	56.4	10.4	60

1. Performance values and curves in this data sheet were measured in this fixture.



Functional Schematic



Pin Configuration

Pin #	Pin Name	Function
1	RF_{IN} / V_G	RF Input / Gate
2	RF_{OUT} / V_D	RF Output / Drain
3	Flange ²	Ground / Source

2. The flange on the package bottom must be connected to RF, DC and thermal ground.

Ordering Information

Part Number	MOQ Increment
CGHV35400F1	Bulk
CGHV35400F1-AMP	Sample Board

* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

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DC Electrical Characteristics @ T_c = +25°C

Characteristics	Symbol	Conditions	Units	Min.	Тур.	Max.
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = 10 V, I _D = 83.6 mA	V	-3.8	-3.0	-2.3
Gate Quiescent Voltage	V _{GS(Q)}	V_{DS} = 50 V, I _D = 500 mA	V	_	-2.7	—
Saturated Drain Current ⁴	I _{DS}	V_{DS} = 6 V, V_{GS} = 2 V	А	62.7	75.5	—
Drain-Source Breakdown Voltage	V _{BR}	V_{GS} = -8 V, I _D = 83.6 mA	V	125		—

4. Scaled from PCM data.

RF Electrical Characteristics⁵ @ T_c = +25°C, Freq. = 2.9 - 3.5 GHz, V_{DD} = 50 V, I_{DQ} = 500 mA

Characteristics	Symbol	Conditions	Units	Min.	Тур.	Max.
Small Signal Gain	S21	P _{IN} = -20 dBm	dB	—	13.7	—
Input Return Loss	S11	P _{IN} = -20 dBm	dB	_	7.1	—
Output Return Loss	S22	P _{IN} = -20 dBm	dB		5.8	—
Power Gain	G _P	P _{IN} = 46 dBm 2.9 GHz 3.2 GHz 3.5 GHz	dB	10.0	11.2 11.0 10.7	
Output Power	P _{OUT}	P _{IN} = 46 dBm 2.9 GHz 3.2 GHz 3.5 GHz	dBm	56.0	57.2 57.1 56.7	
Drain Efficiency	D _E	P _{IN} = 46 dBm 2.9 GHz 3.2 GHz 3.5 GHz	%	54	68 63 62	
Output Mismatch Stress	VSWR	No damage at all phase angles	Ψ	—	—	3:1

5. Pulse Width = 500 μ s, Duty Cycle = 10%.

Thermal Characteristics

Parameter	Symbol	Test Conditions	Units	Rating
Operating Junction Temperature	TJ	Pulse Width = 2 ms, Duty Cycle = 20%,	°C	224
Thermal Resistance, Junction to Case	$R_{\theta JC}$	$P_{DISS} = 418 \text{ W}, T_{C} = 57.2^{\circ}\text{C}$	°C/W	0.4

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Rev. V3

Parameter	Symbol	Conditions	Units	Rating
Drain-Source Voltage	V _{DSS}	25°C	V	150
Gate-Source Voltage	V _{GS}	25°C	V	-10 to +2
Maximum Forward Gate Current	I _{GMAX}	25°C	mA	80
DC Drain Current	IDMAX	25°C	А	12
Soldering Temperature	Ts	—	°C	245
Pulse Width	PW	_	mS	2000
Duty Cycle	DC	—	%	20
Operating Junction Temperature	TJ	MTTF > 1e6 Hours	°C	225
Storage Temperature	T _{STG}	_	°C	-65 to +150

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

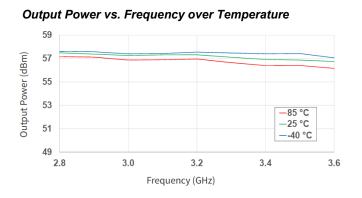
These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 3A and CDM C3 Class devices.

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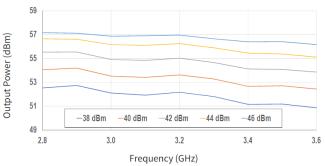


Typical Performance Curves:

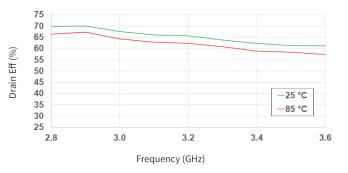
 V_D = 50 V, I_{DQ} = 500 mA, Pulse Width = 500 µs, Duty Cycle = 10%, P_{IN} = 46 dBm, T_B = +25°C



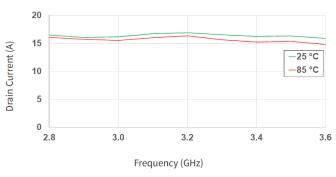
Output Power vs. Frequency over Input Power



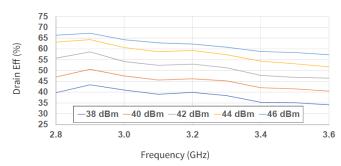
Drain Efficiency vs. Frequency over Temperature



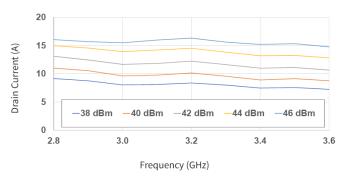




Drain Efficiency vs. Frequency over Input Power



Drain Current vs. Frequency over Input Power



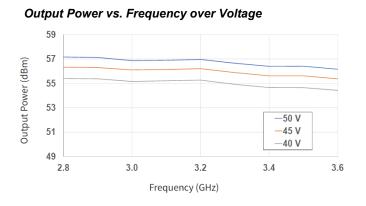
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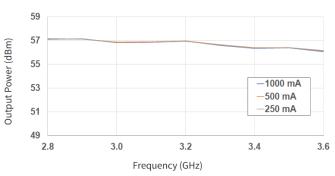


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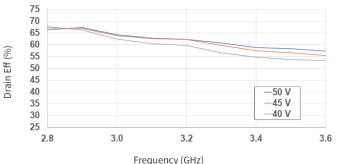
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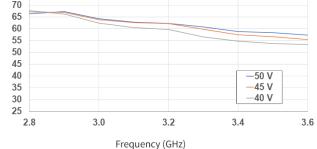


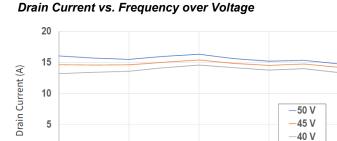
Output Power vs. Frequency over IDQ



Drain Efficiency vs. Frequency over Voltage







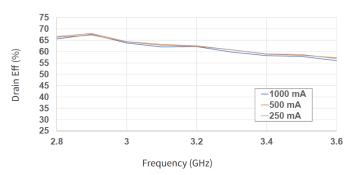
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Frequency (GHz)

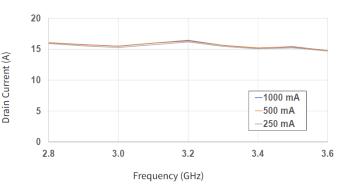
3.4

3.0

Drain Efficiency vs. Frequency over I_{DQ}



Drain Current vs. Frequency over I_{DQ}



0

2.8

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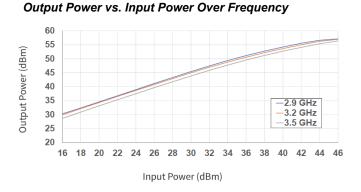
3.6

⁵

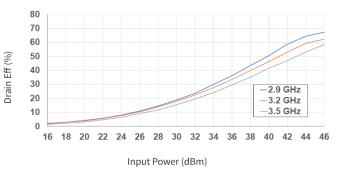


Typical Performance Curves:

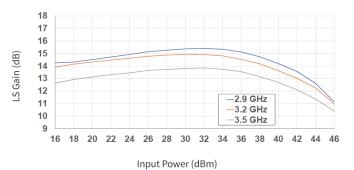
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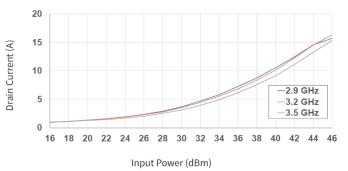
Drain Efficiency vs. Input Power Over Frequency



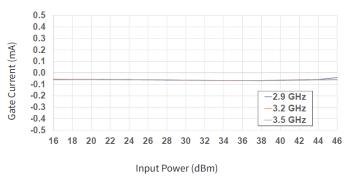
LS Gain vs. Input Power Over Frequency



Drain Current vs. Input Power Over Frequency







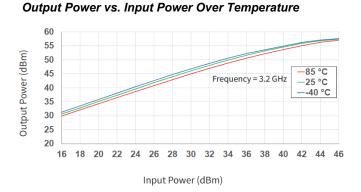
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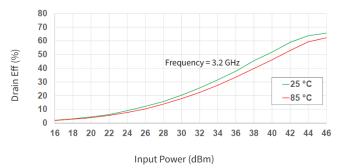


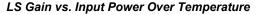
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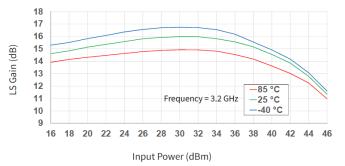
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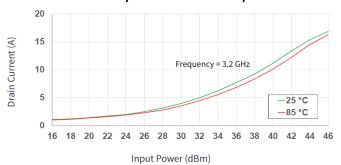
Drain Efficiency vs. Input Power Over Temperature



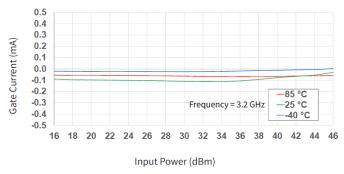




Drain Current vs. Input Power Over Temperature



Gate Current vs. Input Power Over Temperature



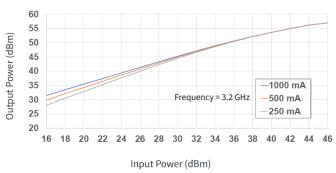
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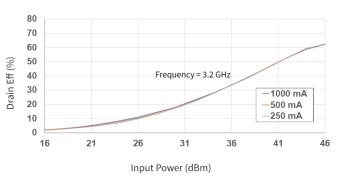
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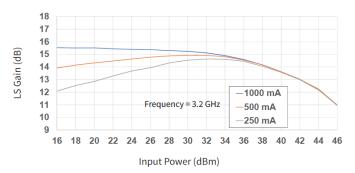
Output Power vs. Input Power Over I_{DQ}



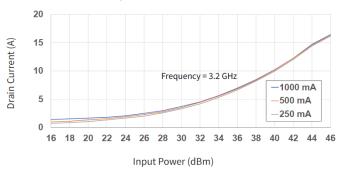
Drain Efficiency vs. Input Power Over IDQ

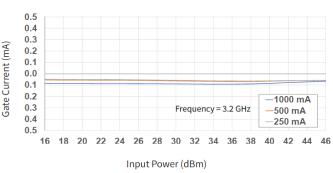


LS Gain vs. Input Power Over IDQ



Drain Current vs. Input Power Over IDQ





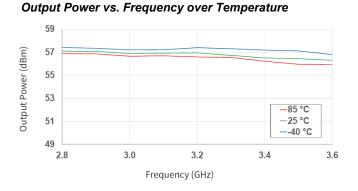
Gate Current vs. Input Power Over IDQ

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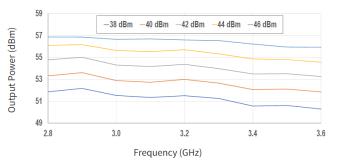


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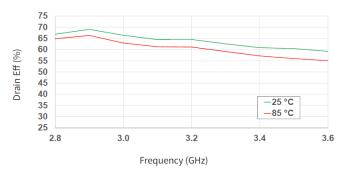
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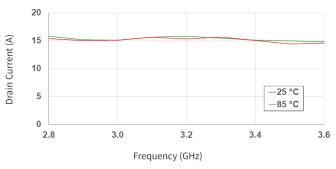
Output Power vs. Frequency over Input Power



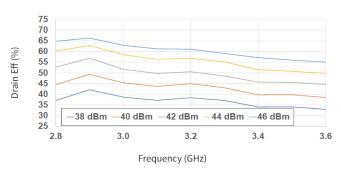
Drain Efficiency vs. Frequency over Temperature



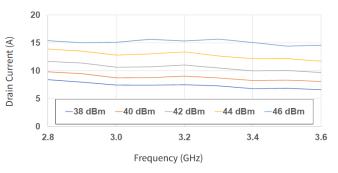




Drain Efficiency vs. Frequency over Input Power



Drain Current vs. Frequency over Input Power



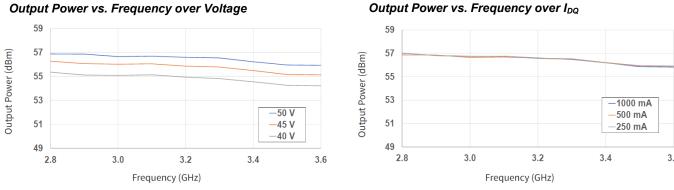
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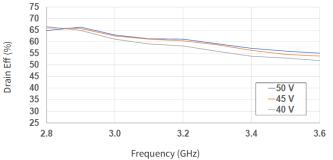
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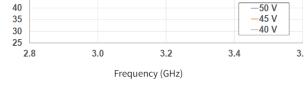
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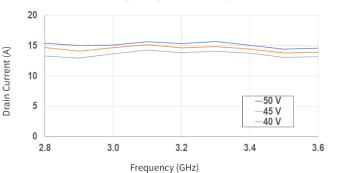


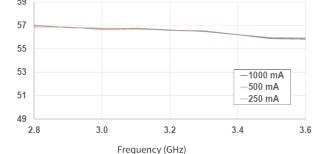
Drain Efficiency vs. Frequency over Voltage



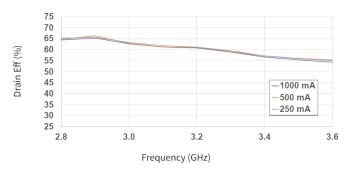


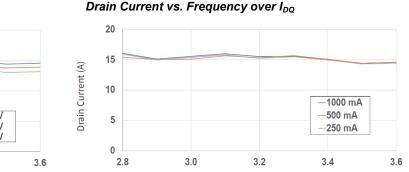






Drain Efficiency vs. Frequency over I_{DQ}





Frequency (GHz)

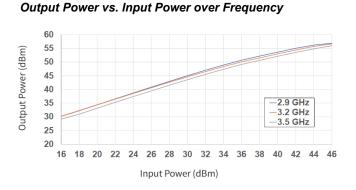
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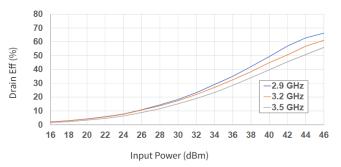


Typical Performance Curves:

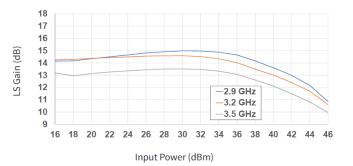
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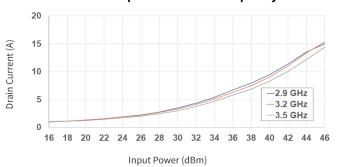
Drain Efficiency vs. Input Power over Frequency

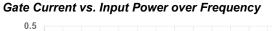


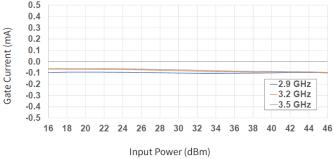
LS Gain vs. Input Power over Frequency



Drain Current vs. Input Power over Frequency





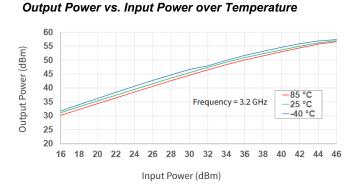


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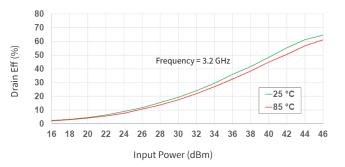


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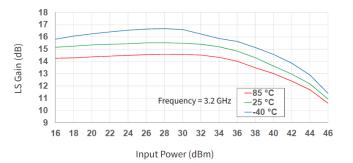
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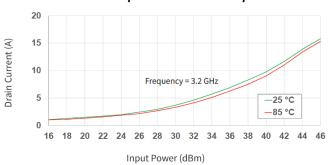
Drain Efficiency vs. Input Power over Temperature

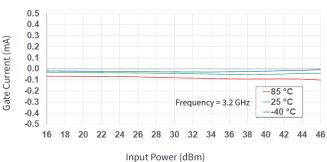


LS Gain vs. Input Power over Temperature



Drain Current vs. Input Power over Temperature





Gate Current vs. Input Power over Temperature

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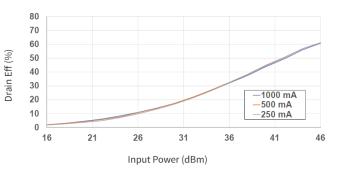
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Typical Performance Curves:

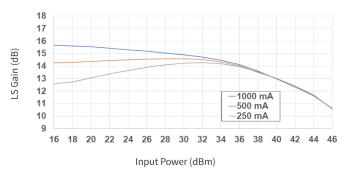
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Output Power vs. Input Power over IDQ 60 55 Output Power (dBm) 50 45 40 35 1000 mA 30 500 mA 250 mA 25 20 16 18 20 22 24 26 28 30 32 34 36 38 40 42 44 46 Input Power (dBm)

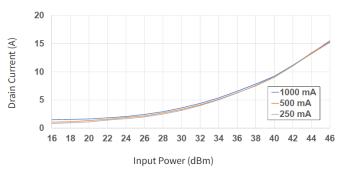
Drain Efficiency vs. Input Power over IDQ

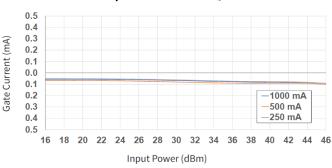


LS Gain vs. Input Power over IDQ



Drain Current vs. Input Power over IDQ





Gate Current vs. Input Power over IDQ

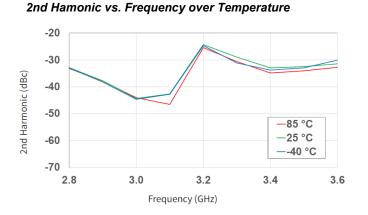
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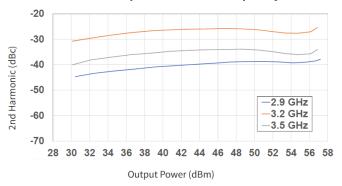


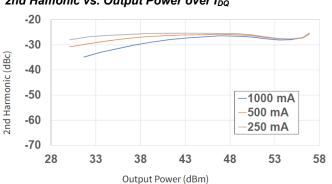
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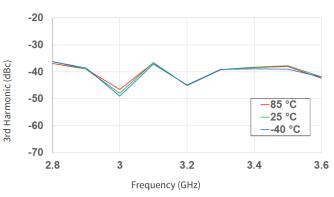
2nd Hamonic vs. Output Power over Frequency



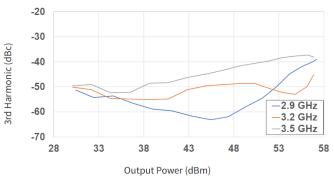


2nd Hamonic vs. Output Power over IDQ

3rd Hamonic vs. Frequency over Temperature



3rd Hamonic vs. Output Power over Frequency





14

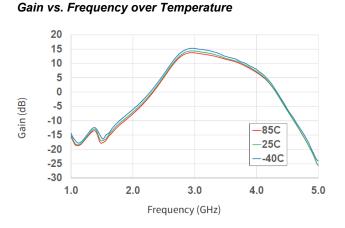
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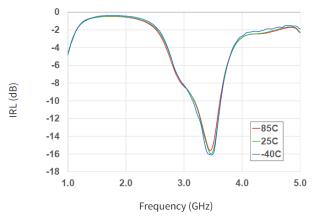


Typical Performance Curves:

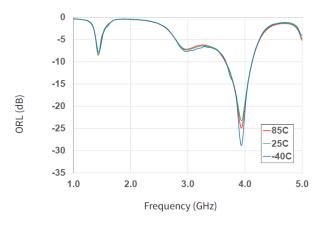




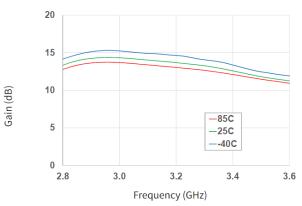
Input Return Loss vs. Frequency over Temperature



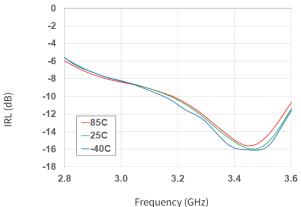
Output Return Loss vs. Frequency over Temperature



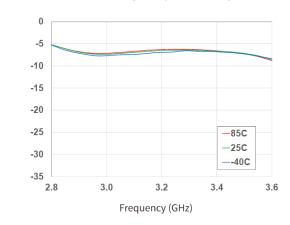
Gain vs. Frequency over Temperature



Input Return Loss vs. Frequency over Temperature



Output Return Loss vs. Frequency over Temperature



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ORL (dB)

¹⁵

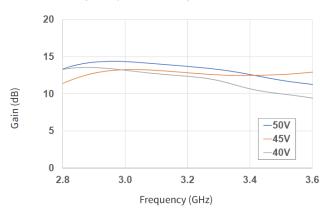


CGHV35400F1 Rev. V3

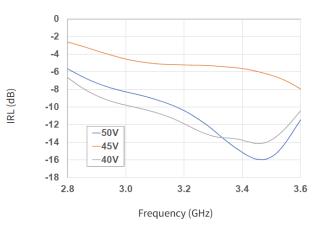
Typical Performance Curves:



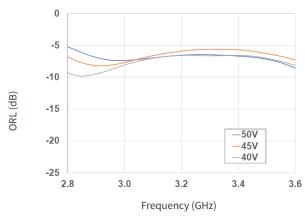
Gain vs. Frequency over Voltage



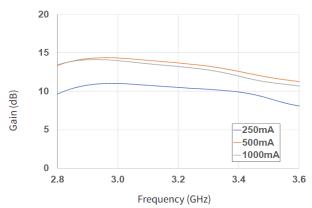
Input Return Loss vs. Frequency over Voltage



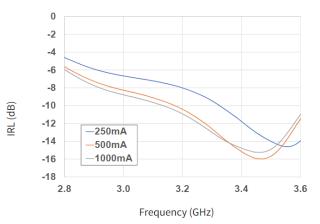
Output Return Loss vs. Frequency over Voltage



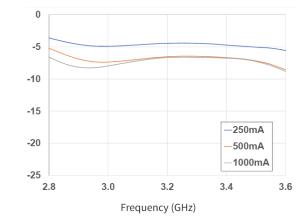
Gain vs. Frequency over IDQ



Input Return Loss vs. Frequency over IDQ



Output Return Loss vs. Frequency over IDQ



16

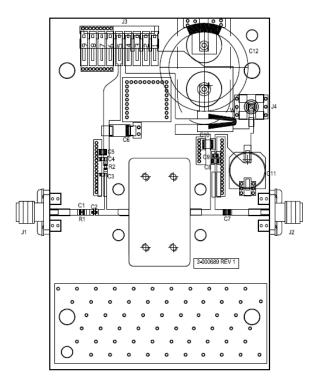
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ORL (dB)



CGHV35400F1 Rev. V3

Assembly Drawing



Parts List

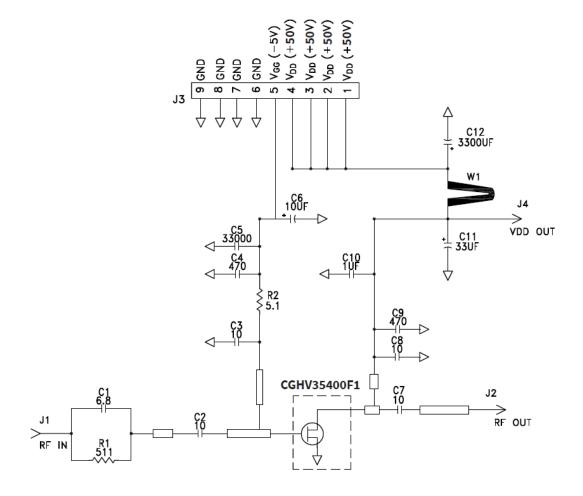
Designator	Description	QTY.
C1	CAP, 6.8 pF, +/-0.25%, 250V, 0603	1
C2, C7, C8	CAP, 10 pF, +/-1%, 250V, 0805	3
C3	CAP, 10 pF, +/-5%, 250V, 0603	1
C4, C9	CAP, 470 pF, 5%, 100V, 0603, X	2
C5	CAP, 33000 pF, 0805, 100V, X7R	1
C6	CAP, 10 μF, 16V, TANTALUM	1
C10	CAP, 1 µF, 100V, 10%, X7R, 1210	1
C11	CAP, 33 µF, 20%, G CASE	1
C12	CAP, 3300 µF, +/-20%, 100V, ELECTROLYTIC	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FL	2
J3	HEADER, RT>PLZ, 0.1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
R1	RES, 511 Ω, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1 Ω, +/- 1%, 1/16W, 0603	1
W1	CABLE, 18 AWG, 4.2	1
—	PCB, RO4350, 2.5 X 4.0 X 0.030	1
Q1	CGHV35400F1	1

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CGHV35400F1 Rev. V3

Application Circuit Schematic



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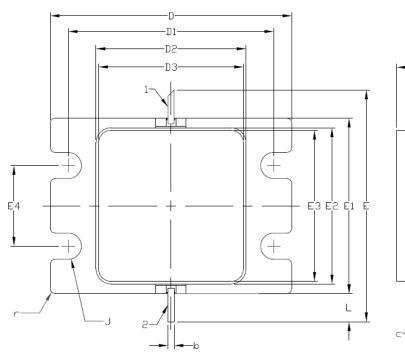


CGHV35400F1 Rev. V3

Product Dimensions (Package Type 440226)

NOTES: (UNLESS OTHERWISE SPECIFIED)

- 1. INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-2009
- 2. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF .020 BEYOND EDGE OF LID
- 3. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF .008 IN ANY DIRECTION
- 4. ALL PLATED SURFACES ARE GOLD OVER NICKEL



		00)2	1. GATE 2. DRAIN		4		
-A-	-			INC	HES	MILLIMETERS		NOTES
-	-	—A1	DIM	MIN	MAX	MIN	MAX	
i			А	0.185	0.201	4.70	5.11	
			A1	0.088	0.100	2.24	2.54	2x
			A2	0.049	0.061	1.24	1.55	
			b	0.022	0.026	0.56	0.66	2x
			С	0.003	0.006	0.08	0.15	
			D	0.935	0.955	23.75	24.26	
			D1	0.797	0.809	20.24	20.55	2x
			D2	0.581	0.593	14.76	15.06	
			D3	0.565	0.571	14.35	14.50	
			E	0.9	906	23	.01	REF
			E1	0.679	0.691	17.25	17.55	
			E2	0.604	0.616	15.34	15.65	
			E3	0.588	0.594	14.93	15.09	
			E4	0.309	0.321	7.85	8.15	2x
			J	ø0.097	ø0.107	ø2.46	ø2.72	4×
			L	0.090	0.130	2.29	3.30	2x
			r	0.02	TYP	0.51	TYP	12x
- -	_	- A2	2					

Pin #	Description
1	Gate / RFIN
2	Drain / RFOUT
3	Source / Flange

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